

## Gas Gauge IC for High Discharge Rates

### Features

- ▶ Conservative and repeatable measurement of available charge in rechargeable batteries
- ▶ Designed for portable equipment such as power tools with high discharge rates
- ▶ Designed for battery pack integration
  - 120µA typical standby current (self-discharge estimation mode)
  - Small size enables implementations in as little as ½ square inch of PCB
- ▶ Direct drive of LEDs for capacity display
- ▶ Self-discharge compensation using internal temperature sensor
- ▶ Simple single-wire serial communications port for subassembly testing
- ▶ 16-pin narrow SOIC

### General Description

The bq2011 Gas Gauge IC is intended for battery-pack installation to maintain an accurate record of available battery charge. The IC monitors a voltage drop across a sense resistor connected in series between the negative battery terminal and ground to determine charge and discharge activity of the battery. The bq2011 is designed for systems such as power tools with very high discharge rates.

Battery self-discharge is estimated based on an internal timer and temperature sensor. Compensations for battery temperature and rate of charge or discharge are applied to the charge, discharge, and self-discharge calculations to provide available charge information across a wide range of operating conditions. Initial battery capacity is set using the PFC and MODE pins. Actual battery capacity is automatically “learned” in the course of a discharge cycle from full to empty and may be displayed depending on the display mode.

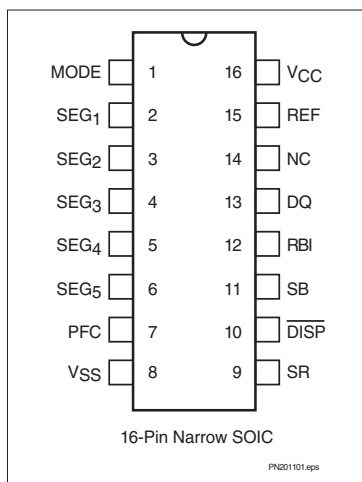
Nominal available charge may be directly indicated using a five-segment LED display. These segments are used to indicate graphically the nominal available charge.

The bq2011 supports a simple single-line bidirectional serial link to an external processor (common ground). The bq2011 outputs battery information in response to external commands over the serial link. To support subassembly testing, the outputs may also be controlled by command. The external processor may also overwrite some of the bq2011 gas gauge data registers.

The bq2011 may operate directly from four cells. With the REF output and an external transistor, a simple, inexpensive regulator can be built to provide V<sub>CC</sub> from a greater number of cells.

Internal registers include available charge, temperature, capacity, battery ID, and battery status.

### Pin Connections



### Pin Names

MODE	Display mode output	NC	No connect
SEG <sub>1</sub>	LED segment 1	DQ	Serial communications input/output
SEG <sub>2</sub>	LED segment 2	RBI	Register backup input
SEG <sub>3</sub>	LED segment 3	SB	Battery sense input
SEG <sub>4</sub>	LED segment 4	$\overline{\text{DISP}}$	Display control input
SEG <sub>5</sub>	LED segment 5	SR	Sense resistor input
PFC	Programmed full count selection input	V <sub>CC</sub>	3.0–6.5V
REF	Voltage reference output	V <sub>SS</sub>	Negative battery terminal

## Pin Descriptions

### MODE    Display mode output

When left floating, this output selects relative mode for capacity display. If connected to the anode of the LEDs to source current, absolute mode is selected for capacity display. See Table 1.

### SEG<sub>1</sub>– SEG<sub>5</sub>    LED display segment outputs

Each output may activate an LED to sink the current sourced from MODE, the battery, or V<sub>CC</sub>.

### PFC    Programmed full count selection input

This three-level input pin defines the programmed full count (PFC) thresholds and scale selections described in Table 1. The state of the PFC pin is only read immediately after a reset condition.

### SR    Sense resistor input

The voltage drop (V<sub>SR</sub>) across the sense resistor R<sub>S</sub> is monitored and integrated over time to interpret charge and discharge activity. The SR input is tied to the low side of the sense resistor. V<sub>SR</sub> > V<sub>SS</sub> indicates discharge, and V<sub>SR</sub> < V<sub>SS</sub> indicates charge. The effective voltage drop, V<sub>SRO</sub>, as seen by the bq2011 is V<sub>SR</sub> + V<sub>OS</sub> (see Table 3).

### NC    No connect

### $\overline{\text{DISP}}$

#### Display control input

$\overline{\text{DISP}}$  floating allows the LED display to be active during charge and discharge if V<sub>SRO</sub> < -1mV (charge) or V<sub>SRO</sub> > 2mV (discharge). Transitioning  $\overline{\text{DISP}}$  low activates the display for 4 ± 0.5 seconds.

### SB

#### Secondary battery input

This input monitors the single-cell voltage potential through a high-impedance resistive divider network for the end-of-discharge voltage (EDV) threshold and maximum cell voltage (MCV).

### RBI

#### Register backup input

This input is used to provide backup potential to the bq2011 registers during periods when V<sub>CC</sub> ≤ 3V. A storage capacitor should be connected to RBI.

### DQ

#### Serial I/O pin

This is an open-drain bidirectional pin.

### REF

#### Voltage reference output for regulator

REF provides a voltage reference output for an optional micro-regulator.

### V<sub>CC</sub>

#### Supply voltage input

### V<sub>SS</sub>

#### Ground

# bq2011

## Functional Description

### General Operation

The bq2011 determines battery capacity by monitoring the amount of charge input to or removed from a rechargeable battery. The bq2011 measures discharge and charge currents, estimates self-discharge, monitors the battery for low-battery voltage thresholds, and compensates for temperature and charge/discharge rates. The charge measurement is made by monitoring the voltage across a small-value series sense resistor between the negative battery terminal and ground. The available battery charge is determined by monitoring this voltage over time and correcting the measurement for the environmental and operating conditions.

Figure 1 shows a typical battery pack application of the bq2011 using the LED display with absolute mode as a charge-state indicator. The bq2011 can be configured to display capacity in either a relative or an absolute display mode. The relative display mode uses the last measured discharge capacity of the battery as the battery “full” reference. The absolute display mode uses the programmed full count (PFC) as the full reference, forcing each segment of the display to represent a fixed amount of charge. A push-button display feature is available for momentarily enabling the LED display.

The bq2011 monitors the charge and discharge currents as a voltage across a sense resistor (see  $R_S$  in Figure 1). A filter between the negative battery terminal and the SR pin may be required if the rate of change of the battery current is too great.

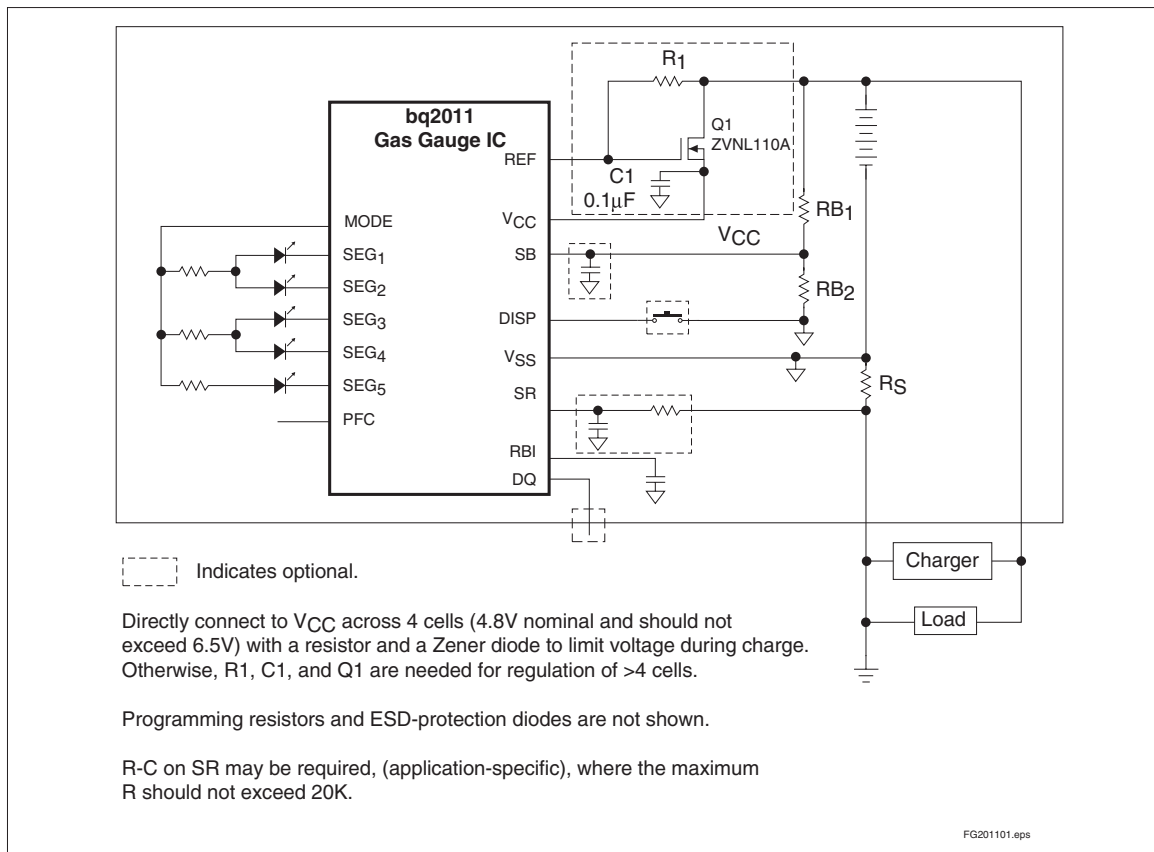


Figure 1. Battery Pack Application Diagram—LED Display, Absolute Mode

### Register Backup

The bq2011 RBI input pin is intended to be used with a storage capacitor to provide backup potential to the internal bq2011 registers when  $V_{CC}$  momentarily drops below 3.0V.  $V_{CC}$  is output on RBI when  $V_{CC}$  is above 3.0V.

After  $V_{CC}$  rises above 3.0V, the bq2011 checks the internal registers for data loss or corruption. If data has changed, then the NAC and FULCNT registers are cleared, and the LMD register is loaded with the initial PFC.

### Voltage Thresholds

In conjunction with monitoring  $V_{SR}$  for charge/discharge currents, the bq2011 monitors the single-cell battery potential through the SB pin. The single-cell voltage potential is determined through a resistor-divider network per the following equation:

$$\frac{RB_1}{RB_2} = N - 1$$

where N is the number of cells,  $RB_1$  is connected to the positive battery terminal, and  $RB_2$  is connected to the negative battery terminal. The single-cell battery voltage is monitored for the end-of-discharge voltage (EDV) and for maximum cell voltage (MCV). The EDV threshold level is used to determine when the battery has reached an “empty” state, and the MCV threshold is used for fault detection during charging. The EDV and MCV thresholds for the bq2011 are fixed at:

$$\begin{aligned} V_{EDV} &= 0.90V \\ V_{MCV} &= 2.00V \end{aligned}$$

During discharge and charge, the bq2011 monitors  $V_{SR}$  for various thresholds,  $V_{SR1}$ – $V_{SR4}$ . These thresholds are used to compensate the charge and discharge rates. Refer to the discharge compensation section for details. EDV monitoring is disabled if  $V_{SR} \geq V_{SR1}$  (50mV typical) and resumes 1 second after  $V_{SR}$  drops back below  $V_{SR1}$ .

### Reset

The bq2011 recognizes a valid battery whenever  $V_{SB}$  is greater than 0.1V typical.  $V_{SB}$  rising from below 0.25V resets the device. Reset can also be accomplished with a command over the serial port as described in the Reset Register section.

### Temperature

The bq2011 internally determines the temperature in 10°C steps centered from -35°C to +85°C. The temperature steps are used to adapt charge and discharge rate compensations, self-discharge counting, and available

charge display translation. The temperature range is available over the serial port in 10°C increments as shown below:

TMPGG (hex)	Temperature Range
0x	< -30°C
1x	-30°C to -20°C
2x	-20°C to -10°C
3x	-10°C to 0°C
4x	0°C to 10°C
5x	10°C to 20°C
6x	20°C to 30°C
7x	30°C to 40°C
8x	40°C to 50°C
9x	50°C to 60°C
Ax	60°C to 70°C
Bx	70°C to 80°C
Cx	> 80°C

### Layout Considerations

The bq2011 measures the voltage differential between the SR and  $V_{SS}$  pins.  $V_{OS}$  (the offset voltage at the SR pin) is greatly affected by PC board layout. For optimal results, the PC board layout should follow the strict rule of a single-point ground return. Sharing high-current ground with small signal ground causes undesirable noise on the small signal nodes. Additionally:

- The capacitors (SB and  $V_{CC}$ ) should be placed as close as possible to the SB and  $V_{CC}$  pins, respectively, and their paths to  $V_{SS}$  should be as short as possible. A high-quality ceramic capacitor of 0.1µf is recommended for  $V_{CC}$ .
- The sense resistor ( $R_S$ ) should be as close as possible to the bq2011.
- The R-C on the SR pin should be located as close as possible to the SR pin. The maximum R should not exceed 20K.

# bq2011

## Gas Gauge Operation

The operational overview diagram in Figure 2 illustrates the operation of the bq2011. The bq2011 accumulates a measure of charge and discharge currents, as well as an estimation of self-discharge. Charge and discharge currents are temperature and rate compensated, whereas self-discharge is only temperature compensated.

The main counter, Nominal Available Charge (NAC), represents the available battery capacity at any given time. Battery charging increments the NAC register, while battery discharging and self-discharge decrement the NAC register and increment the DCR (Discharge Count Register).

The Discharge Count Register (DCR) is used to update the Last Measured Discharge (LMD) register only if a complete battery discharge from full to empty occurs without any partial battery charges. Therefore, the bq2011 adapts its capacity determination based on the actual conditions of discharge.

The battery's initial capacity is equal to the Programmed Full Count (PFC) shown in Table 1. Until LMD is updated, NAC counts up to but not beyond this threshold during subsequent charges. This approach allows the gas gauge to be charger-independent and compatible with any type of charge regime.

### 1. Last Measured Discharge (LMD) or learned battery capacity:

LMD is the last measured discharge capacity of the battery. On initialization (application of  $V_{CC}$  or battery replacement),  $LMD = PFC$ . During subsequent discharges, the LMD is updated with the latest measured capacity in the Discharge Count Register (DCR) representing a discharge from full to below EDV. A qualified discharge is necessary for a capacity transfer from the DCR to the LMD register. The LMD also serves as the 100% reference threshold used by the relative display mode.

### 2. Programmed Full Count (PFC) or initial battery capacity:

The initial LMD and gas gauge rate values are programmed by using PFC. The PFC also provides the 100% reference for the absolute display mode. The bq2011 is configured for a given application by selecting a PFC value from Table 1. The correct PFC may be determined by multiplying the rated battery capacity in mAh by the sense resistor value:

$$\text{Battery capacity (mAh)} * \text{sense resistor } (\Omega) = \text{PFC (mVh)}$$

Selecting a PFC slightly less than the rated capacity for absolute mode provides capacity above the full reference for much of the battery's life.

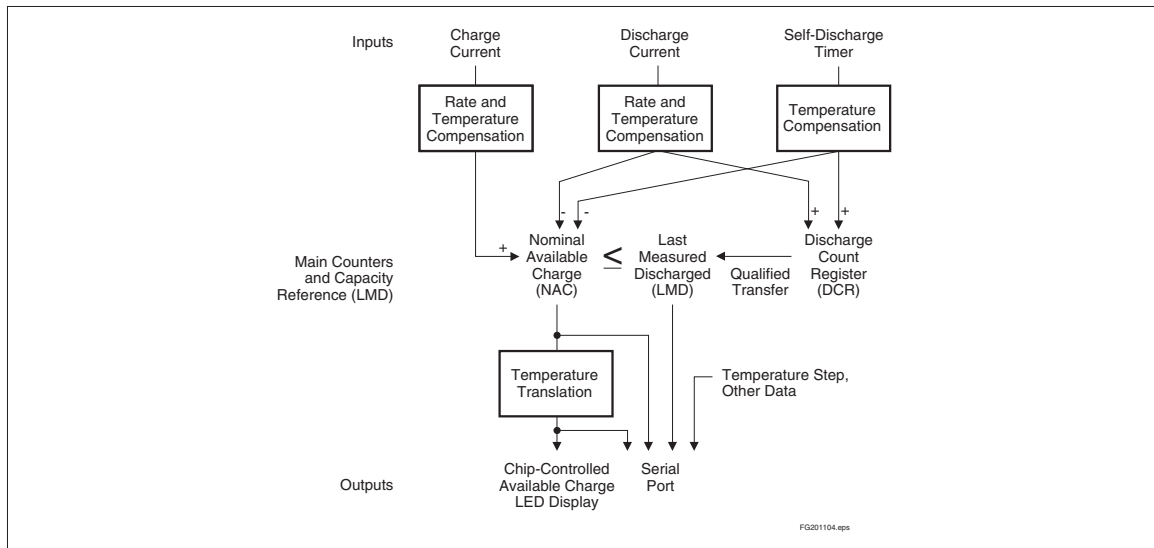


Figure 2. Operational Overview

**Example: Selecting a PFC Value**

Given:

- Sense resistor = 0.005Ω
- Number of cells = 6
- Capacity = 1300mAh, NiCd cells
- Current range = 1A to 80A
- Relative display mode
- Self-discharge = %<sub>64</sub>
- Voltage drop over sense resistor = 5mV to 400mV

Therefore:

$1300\text{mAh} * 0.005\Omega = 6.5\text{mVh}$

Select:

- PFC = 34304 counts or 6.5mVh
- PFC = Z (float)
- MODE = not connected

The initial full battery capacity is 6.5mVh (1300mAh) until the bq2011 “learns” a new capacity with a qualified discharge from full to EDV.

**Table 1. bq2011 Programmed Full Count mVh Selections**

PFC	Programmed Full Count (PFC)	mVh	Scale	MODE Pin	Display Mode
H	27648	10.5	$\frac{1}{2640}$	Floating	Relative
Z	34304	6.5	$\frac{1}{5280}$		
L	44800	8.5	$\frac{1}{5280}$		
H	42240	8.0	$\frac{1}{5280}$	Connected to LEDs	Absolute
Z	31744	6.0	$\frac{1}{5280}$		
L	23808	4.5	$\frac{1}{5280}$		

## bq2011

### 3. Nominal Available Charge (NAC):

NAC counts up during charge to a maximum value of LMD and down during discharge and self discharge to 0. NAC is reset to 0 on initialization and on the first valid charge following discharge to EDV. To prevent overstatement of charge during periods of overcharge, NAC stops incrementing when NAC = LMD.

**Note:** NAC is set to the value in LMD when SEG<sub>5</sub> is pulled low during a reset.

### 4. Discharge Count Register (DCR):

The DCR counts up during discharge independent of NAC and could continue increasing after NAC has decremented to 0. Prior to NAC = 0 (empty battery), both discharge and self-discharge increment the DCR. After NAC = 0, only discharge increments the DCR. The DCR resets to 0 when NAC = LMD. The DCR does not roll over but stops counting when it reaches FFFFh.

The DCR value becomes the new LMD value on the first charge after a valid discharge to V<sub>EDV</sub> if:

- No valid charge initiations (charges greater than 256 NAC counts; or 0.006 – 0.01C) occurred during the period between NAC = LMD and EDV detected.
- The self-discharge count is not more than 4096 counts (8% to 18% of PFC, specific percentage threshold determined by PFC).
- The temperature is  $\geq 0^{\circ}\text{C}$  when the EDV level is reached during discharge.

The valid discharge flag (VDQ) indicates whether the present discharge is valid for LMD update.

### Charge Counting

Charge activity is detected based on a negative voltage on the V<sub>SR</sub> input. If charge activity is detected, the bq2011 increments NAC at a rate proportional to V<sub>SRO</sub> (V<sub>SR</sub> + V<sub>OS</sub>) and, if enabled, activates an LED display if V<sub>SRO</sub> < -1mV. Charge actions increment the NAC after compensation for charge rate and temperature.

The bq2011 determines a valid charge activity sustained at a continuous rate equivalent to V<sub>SRO</sub> < -400 $\mu\text{V}$ . A valid charge equates to a sustained charge activity greater than 256 NAC counts. Once a valid charge is detected, charge counting continues until V<sub>SRO</sub> rises above -400 $\mu\text{V}$ .

### Discharge Counting

All discharge counts where V<sub>SRO</sub> > 500 $\mu\text{V}$  cause the NAC register to decrement and the DCR to increment. Exceeding the fast discharge threshold (FDQ) if the rate is equivalent to V<sub>SRO</sub> > 2mV activates the display, if enabled. The display becomes inactive after V<sub>SRO</sub> falls below 2mV.

### Self-Discharge Estimation

The bq2011 continuously decrements NAC and increments DCR for self-discharge based on time and temperature. The self-discharge count rate is programmed to be a nominal  $\frac{1}{60} * \text{NAC}$  rate per day. This is the rate for a battery whose temperature is between 20°–30°C. The NAC register cannot be decremented below 0.

### Count Compensations

The bq2011 determines fast charge when the NAC updates at a rate of  $\geq 2$  counts/sec. Charge and discharge activity is compensated for temperature and charge/discharge rate before updating the NAC and/or DCR. Self-discharge estimation is compensated for temperature before updating the NAC or DCR.

### Charge Compensation

Two charge efficiency factors are used for trickle charge and fast charge. Fast charge is defined as a rate of charge resulting in  $\geq 2$  NAC counts/sec ( $\geq 0.15\text{C}$  to  $0.32\text{C}$  depending on PFC selections; see Table 2). The compensation defaults to the fast charge factor until the actual charge rate is determined.

Temperature adapts the charge rate compensation factors over three ranges between nominal, warm, and hot temperatures. The compensation factors are shown below.

Charge Temperature	Trickle Charge Compensation	Fast Charge Compensation
<40°C	0.80	0.95
$\geq 40^{\circ}\text{C}$	0.75	0.90

### Discharge Compensation

Corrections for the rate of discharge are made by adjusting an internal discharge compensation factor. The discharge factor is based on the dynamically measured  $V_{SR}$ . The compensation factors during discharge are:

Approximate $V_{SR}$ Threshold	Discharge Compensation Factor	Efficiency
$V_{SR} < 50$ mV	1.00	100%
$V_{SR1} > 50$ mV	1.05	95%
$V_{SR2} > 100$ mV	1.15	85%
$V_{SR3} > 150$ mV	1.25	75%
$V_{SR4} > 253$ mV	1.25	75%

Temperature compensation during discharge also takes place. At lower temperatures, the compensation factor increases by 0.05 for each 10°C temperature step below 10°C.

$$\text{Comp. factor} = 1.00 + (0.05 * N)$$

Where N = number of 10°C steps below 10°C and  $V_{SR} < 50$ mV.

For example:

T > 10°C: Nominal compensation, N = 0

0°C < T < 10°C: N = 1 (i.e., 1.00 becomes 1.05)

-10°C < T < 0°C: N = 2 (i.e., 1.00 becomes 1.10)

-20°C < T < -10°C: N = 3 (i.e., 1.00 becomes 1.15)

-20°C < T < -30°C: N = 4 (i.e., 1.00 becomes 1.20)

### Self-Discharge Compensation

The self-discharge compensation is programmed for a nominal rate of  $\frac{1}{60} * \text{NAC}$  per day. This is the rate for a battery within the 20–30°C temperature range (TMPGG = 6x). This rate varies across 8 ranges from <10°C to >70°C, doubling with each higher temperature step (10°C). See Table 2

**Table 2. Self-Discharge Compensation**

Temperature Range	Self-Discharge Compensation Typical Rate/Day
< 10°C	$\frac{\text{NAC}}{320}$
10–20°C	$\frac{\text{NAC}}{160}$
20–30°C	$\frac{\text{NAC}}{80}$
30–40°C	$\frac{\text{NAC}}{40}$
40–50°C	$\frac{\text{NAC}}{20}$
50–60°C	$\frac{\text{NAC}}{10}$
60–70°C	$\frac{\text{NAC}}{5}$
> 70°C	$\frac{\text{NAC}}{2.5}$

### Error Summary

#### Capacity Inaccurate

The LMD is susceptible to error on initialization or if no updates occur. On initialization, the LMD value includes the error between the programmed full capacity and the actual capacity. This error is present until a valid discharge occurs and LMD is updated (see the DCR description on page 7). The other cause of LMD error is battery wear-out. As the battery ages, the measured capacity must be adjusted to account for changes in actual battery capacity.

A Capacity Inaccurate counter (CPI) is maintained and incremented each time a valid charge occurs and is reset whenever LMD is updated from the DCR. The counter does not wrap around but stops counting at 255. The capacity inaccurate flag (CI) is set if LMD has not been updated following 64 valid charges.

#### Current-Sensing Error

Table 3 illustrates the current-sensing error as a function of  $V_{SR}$ . A digital filter eliminates charge and discharge counts to the NAC register when  $V_{SRO}$  ( $V_{SR} + V_{OS}$ ) is between -400µV and 500µV.

**Table 3. bq2011 Current-Sensing Errors**

Symbol	Parameter	Typical	Maximum	Units	Notes
INL	Integrated non-linearity error	± 2	± 4	%	Add 0.1% per °C above or below 25°C and 1% per volt above or below 4.25V.
INR	Integrated non-repeatability error	± 1	± 2	%	Measurement repeatability given similar operating conditions.



# bq2011

## Communicating with the bq2011

The bq2011 includes a simple single-pin (DQ plus return) serial data interface. A host processor uses the interface to access various bq2011 registers. Battery characteristics may be easily monitored by adding a single contact to the battery pack. The open-drain DQ pin on the bq2011 should be pulled up by the host system, or may be left floating if the serial interface is not used.

The interface uses a command-based protocol, where the host processor sends a command byte to the bq2011. The command directs the bq2011 to either store the next eight bits of data received to a register specified by the command byte or output the eight bits of data specified by the command byte.

The communication protocol is asynchronous return-to-one. Command and data bytes consist of a stream of eight bits that have a maximum transmission rate of 333 bits/sec. The least-significant bit of a command or data byte is transmitted first. The protocol is simple enough that it can be implemented by most host processors using either polled or interrupt processing. Data input from the bq2011 may be sampled using the pulse-width capture timers available on some microcontrollers.

Communication is normally initiated by the host processor sending a BREAK command to the bq2011. A BREAK is detected when the DQ pin is driven to a logic-low state for a time,  $t_B$  or greater. The DQ pin should then be returned to its normal ready-high logic state for a time,  $t_{BR}$ . The bq2011 is now ready to receive a command from the host processor.

The return-to-one data bit frame consists of three distinct sections. The first section is used to start the transmission by either the host or the bq2011 taking the DQ pin to a

logic-low state for a period,  $t_{STRH,B}$ . The next section is the actual data transmission, where the data should be valid by a period,  $t_{DSU}$ , after the negative edge used to start communication. The data should be held for a period,  $t_{DV}$ , to allow the host or bq2011 to sample the data bit.

The final section is used to stop the transmission by returning the DQ pin to a logic-high state by at least a period,  $t_{SSU}$ , after the negative edge used to start communication. The final logic-high state should be held until a period,  $t_{SV}$ , to allow time to ensure that the bit transmission was stopped properly. The timings for data and break communication are given in the serial communication timing specification and illustration sections.

Communication with the bq2011 is always performed with the least-significant bit being transmitted first. Figure 3 shows an example of a communication sequence to read the bq2011 NAC register.

## bq2011 Registers

The bq2011 command and status registers are listed in Table 4 and described below.

### Command Register (CMDR)

The write-only CMDR register is accessed when eight valid command bits have been received by the bq2011. The CMDR register contains two fields:

- $W/\overline{R}$  bit
- Command address

The  $W/\overline{R}$  bit of the command register is used to select whether the received command is for a read or a write function.

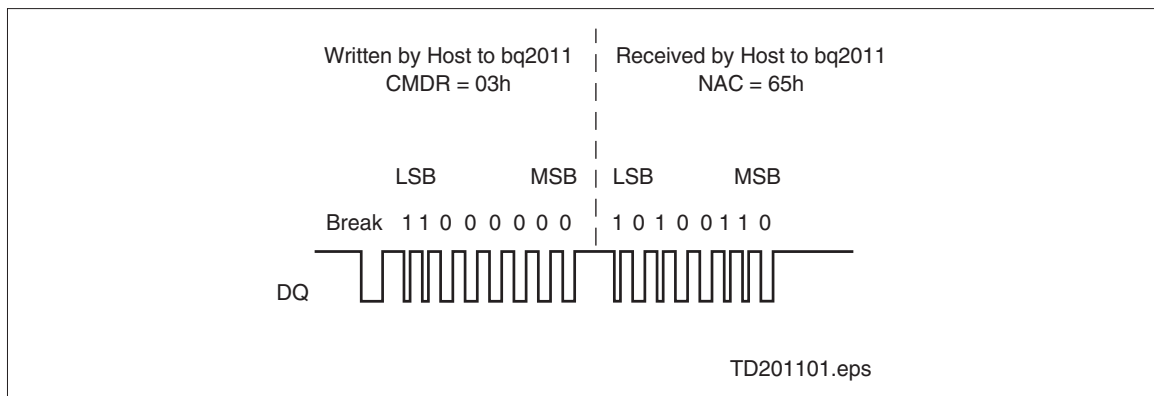


Figure 3. Typical Communication with the bq2011

Table 4. bq2011 Command and Status Registers

Symbol	Register Name	Loc. (hex)	Read/Write	Control Field							
				7(MSB)	6	5	4	3	2	1	0(LSB)
CMDR	Command register	00h	Write	W/R	AD6	AD5	AD4	AD3	AD2	AD1	AD0
FLGS1	Primary status flags register	01h	Read	CHGS	BRP	MCV	CI	VDQ	n/u	EDV	n/u
TMPGG	Temperature and gas gauge register	02h	Read	TMP3	TMP2	TMP1	TMP0	GG3	GG2	GG1	GG0
NACH	Nominal available charge high byte register	03h	R/W	NACH7	NACH6	NACH5	NACH4	NACH3	NACH2	NACH1	NACH0
NACL	Nominal available charge low byte register	17h	Read	NACL7	NACL6	NACL5	NACL4	NACL3	NACL2	NACL1	NACL0
BATID	Battery identification register	04h	R/W	BATID7	BATID6	BATID5	BATID4	BATID3	BATID2	BATID1	BATID0
LMD	Last measured discharge register	05h	R/W	LMD7	LMD6	LMD5	LMD4	LMD3	LMD2	LMD1	LMD0
FLGS2	Secondary status flags register	06h	Read	CR	DR2	DR1	DR0	n/u	n/u	n/u	OVLD
CPI	Capacity inaccurate count register	09h	Read	CPI7	CPI6	CPI5	CPI4	CPI3	CPI2	CPI1	CPI0
OCTL	Output control register	0ah	Write	1	OC5	OC4	OC3	OC2	OC1	n/u	OCE
FULCNT	Full count register	0bh	Read	FUL7	FUL6	FUL5	FUL4	FUL3	FUL2	FUL1	FUL0
RST	Reset register	39h	Write	RST	0	0	0	0	0	0	0

**Note:** n/u = not used

## bq2011

The W/R values are:

CMDR Bits							
7	6	5	4	3	2	1	0
W/R	-	-	-	-	-	-	-

Where W/R is:

- 0 The bq2011 outputs the requested register contents specified by the address portion of CMDR.
- 1 The following eight bits should be written to the register specified by the address portion of CMDR.

The lower seven-bit field of CMDR contains the address portion of the register to be accessed. Attempts to write to invalid addresses are ignored.

CMDR Bits							
7	6	5	4	3	2	1	0
-	AD6	AD5	AD4	AD3	AD2	AD1	AD0 (LSB)

### Primary Status Flags Register (FLGS1)

The read-only FLGS1 register (address=01h) contains the primary bq2011 flags.

The **charge status** flag (CHGS) is asserted when a valid charge rate is detected. Charge rate is deemed valid when  $V_{SRO} < -400\mu V$ . A  $V_{SRO}$  of greater than  $-400\mu V$  or discharge activity clears CHGS.

The CHGS values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
CHGS	-	-	-	-	-	-	-

Where CHGS is:

- 0 Either discharge activity detected or  $V_{SRO} < -400\mu V$
- 1  $V_{SRO} < -400\mu V$

The **battery replaced** flag (BRP) is asserted whenever the potential on the SB pin (relative to  $V_{SS}$ ),  $V_{SB}$ , rises above 0.1V and determines the internal registers have been corrupted. The BRP flag is also set when the bq2011 is reset (see the RST register description). BRP is latched until either the bq2011 is charged until NAC = LMD or discharged until EDV is reached. BRP = 1 signifies that the device has been reset.

The BRP values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	BRP	-	-	-	-	-	-

Where BRP is:

- 0 bq2011 is charged until NAC = LMD or discharged until the EDV flag is asserted
- 1 SB rising from below 0.1V, or a serial port initiated reset has occurred

The **maximum cell voltage** flag (MCV) is asserted whenever the potential on the SB pin (relative to  $V_{SS}$ ) is above 2.0V. The MCV flag is asserted until the condition causing MCV is removed.

The MCV values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	MCV	-	-	-	-	-

Where MCV is:

- 0  $V_{SB} < 2.0V$
- 1  $V_{SB} > 2.0V$

The **capacity inaccurate** flag (CI) is used to warn the user that the battery has been charged a substantial number of times since LMD has been updated. The CI flag is asserted on the 64th charge after the last LMD update or when the bq2011 is reset. The flag is cleared after an LMD update.

The CI values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	-	CI	-	-	-	-

Where CI is:

- 0 When LMD is updated with a valid full discharge or the bq2011 is reset
- 1 After the 64th valid charge action with no LMD updates

The **valid discharge** flag (VDQ) is asserted when the bq2011 is discharged from NAC=LMD. The flag remains set until either LMD is updated or one of three actions that can clear VDQ occurs:

- The self-discharge count register (SDCR) has exceeded the maximum acceptable value (4096 counts) for an LMD update.
- A valid charge action equal to 256 NAC counts with  $V_{SR0} < -400\mu V$ .
- The EDV flag was set at a temperature below 0°C

The VDQ values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	-	-	VDQ	-	-	-

Where VDQ is:

- 0 SDCR  $\geq$  4096, subsequent valid charge action detected, or EDV is asserted with the temperature less than 0°C
- 1 On first discharge after NAC = LMD

The **end-of-discharge warning** flag (EDV) warns the user that the battery is empty. SEG1 blinks at a 4Hz rate. EDV detection is disabled if  $V_{SR} > V_{SR1}$ . The EDV flag is latched until a valid charge has been detected.

The EDV values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	-	-	-	-	EDV	-

Where EDV is:

- 0 Valid charge action detected and  $V_{SB} \geq 0.90V$
- 1  $V_{SB} < 0.90V$  providing that  $V_{SR} < V_{SR1}$

### Temperature and Gas Gauge Register (TMPGG)

The read-only TMPGG register (address=02h) contains two data fields. The first field contains the battery temperature. The second field contains the available charge from the battery.

TMPGG Temperature Bits							
7	6	5	4	3	2	1	0
TMP3	TMP2	TMP1	TMP0	-	-	-	

The bq2011 contains an internal temperature sensor. The temperature is used to set charge and discharge efficiency factors as well as to adjust the self-discharge coefficient. The temperature register contents may be translated as shown below.

TMP3	TMP2	TMP1	TMP0	Temperature
0	0	0	0	T < -30°C
0	0	0	1	-30°C < T < -20°C
0	0	1	0	-20°C < T < -10°C
0	0	1	1	-10°C < T < 0°C
0	1	0	0	0°C < T < 10°C
0	1	0	1	10°C < T < 20°C
0	1	1	0	20°C < T < 30°C
0	1	1	1	30°C < T < 40°C
1	0	0	0	40°C < T < 50°C
1	0	0	1	50°C < T < 60°C
1	0	1	0	60°C < T < 70°C
1	0	1	1	70°C < T < 80°C
1	1	0	0	T > 80°C

The bq2011 calculates the available charge as a function of NAC, temperature, and a full reference, either LMD or PFC. The results of the calculation are available via the display port or the gas gauge field of the TMPGG register. The register is used to give available capacity in  $\frac{1}{16}$  increments from 0 to  $\frac{15}{16}$ .

TMPGG Gas Gauge Bits							
7	6	5	4	3	2	1	0
-	-	-	-	GG3	GG2	GG1	GG0

## bq2011

The gas gauge display and the gas gauge portion of the TMPGG register are adjusted for cold temperature dependencies. A piece-wise correction is performed as follows:

Temperature	Available Capacity Calculation
> 0°C	NAC / “Full Reference”
-20°C < T < 0°C	0.75 * NAC / “Full Reference”
< -20°C	0.5 * NAC / “Full Reference”

The adjustment between > 0°C and -20°C < T < 0°C has a 4°C hysteresis.

### Nominal Available Charge Register (NAC)

The read/write NACH register (address=03h) and the read-only NACL register (address=17h) are the main gas gauging registers for the bq2011. The NAC registers are incremented during charge actions and decremented during discharge and self-discharge actions. The correction factors for charge/discharge efficiency are applied automatically to NAC.

On reset, the NACH and NACL registers are cleared to zero. NACL stops counting when NACH reaches zero. When the bq2011 detects a valid charge, NACL resets to zero; *writing to the NAC register affects the available charge counts and, therefore, affects the bq2011 gas gauge operation.*

### Battery Identification Register (BATID)

The read/write BATID register (address=04h) is available for use by the system to determine the type of battery pack. The BATID contents are retained as long as V<sub>CC</sub> is greater than 2V. The contents of BATID have no effect on the operation of the bq2011. There is no default setting for this register.

### Last Measured Discharge Register (LMD)

LMD is a read/write register (address=05h) that the bq2011 uses as a measured full reference. The bq2011 adjusts LMD based on the measured discharge capacity of the battery from full to empty. In this way the bq2011 updates the capacity of the battery. LMD is set to PFC during a bq2011 reset.

### Secondary Status Flags Register (FLGS2)

The read-only FLGS2 register (address=06h) contains the secondary bq2011 flags.

The **charge rate** flag (CR) is used to denote the fast charge regime. Fast charge is assumed whenever a charge action is initiated. The CR flag remains asserted if the charge rate does not fall below 2 counts/sec.

The CR values are:

FLGS2 Bits							
7	6	5	4	3	2	1	0
CR	-	-	-	-	-	-	-

Where CR is:

- 0 When charge rate falls below 2 counts/sec
- 1 When charge rate is above 2 counts/sec

The fast charge regime efficiency factors are used when CR = 1. When CR = 0, the trickle charge efficiency factors are used. The time to change CR varies due to the user-selectable count rates.

The **discharge rate** flags, DR2–0, are bits 6–4.

FLGS2 Bits							
7	6	5	4	3	2	1	0
-	DR2	DR1	DR0	-	-	-	-

They are used to determine the present discharge regime as follows:

DR2	DR1	DR0	V <sub>SR</sub> (V)
0	0	0	V <sub>SR</sub> < 50mV
0	0	1	50mV < V <sub>SR</sub> < 100mV (overload, OVLD=1)
0	1	0	100mV < V <sub>SR</sub> < 150mV
0	1	1	150mV < V <sub>SR</sub> < 253mV
1	0	0	V <sub>SRD</sub> > 253mV

The **overload** flag (OVLD) is asserted when a discharge overload is detected, V<sub>SRD</sub> > 50mV. OVLD remains asserted as long as the condition persists and is cleared when V<sub>SRD</sub> < 50mV.

FLGS2 Bits							
7	6	5	4	3	2	1	0
-	-	-	-	-	-	-	OVLD

DR2–0 and OVLD are set based on the measurement of the voltage at the SR pin relative to V<sub>SS</sub>. The rate at which this measurement is made varies with device activity.

### Full Count Register (FULCNT)

The read-only FULCNT register (address=0bh) provides the system with a diagnostic of the number of times the battery has been fully charged (NAC = LMD). The number of full occurrences can be determined by multiplying the value in the FULCNT register by 16. Any discharge action other than self-discharge allows detection of another full occurrence during the next valid charge action.

### Capacity Inaccurate Count Register (CPI)

The read-only CPI register (address=09h) is used to indicate the number of times a battery has been charged without an LMD update. Because the capacity of a rechargeable battery varies with age and operating conditions, the bq2011 adapts to the changing capacity over time. A complete discharge from full (NAC=LMD) to empty (EDV=1) is required to perform an LMD update assuming there have been no intervening valid charges, the temperature is greater than or equal to 0°C, and the self-discharge counter is less than 4096 counts.

The CPI register is incremented every time a valid charge is detected. The register increments to 255 without rolling over. When the contents of CPI are incremented to 64, the capacity inaccurate flag, CI, is asserted in the FLGS1 register. CPI is reset whenever an update of the LMD register is performed, and the CI flag is also cleared.

### Output Control Register (OCTL)

The write-only OCTL register (address=0ah) provides the system with a means to check the display connections for the bq2011. The segment drivers may be overwritten by data from OCTL when the least-significant bit of OCTL, OCE, is set. The data in bits OC<sub>5-1</sub> of the OCTL register (see Table 4 on page 10 for details) is output onto the segment pins, SEG<sub>5-1</sub>, respectively if OCE=1. *Whenever OCE is written to 1, the MSB of OCTL should be set to a 1.* The OCE register location must be cleared to return the bq2011 to normal operation. OCE may be cleared by either writing the bit to a logic zero via the serial port or by resetting the bq2011 as explained below. **Note:** Whenever the OCTL register is written, the MSB of OCTL should be written to a logic one.

### Reset Register (RST)

The reset register (address=39h) provides the means to perform a software-controlled reset of the device. A full device reset may be accomplished by first writing LMD (address = 05h) to 00h and then writing the RST register contents from 00h to 80h. *Setting any bit other than the most-significant bit of the RST register is **not allowed**, and results in improper operation of the bq2011.*

Resetting the bq2011 sets the following:

- LMD = PFC
- CPI, VDQ, NAC, and OCE = 0 or NAC = LMD when SEG5 = L
- CI and BRP = 1

### Display

The bq2011 can directly display capacity information using low-power LEDs. If LEDs are used, the segment pins should be tied to V<sub>CC</sub>, the battery, or the MODE pin for programming the bq2011.

The bq2011 displays the battery charge state in either absolute or relative mode. In relative mode, the battery charge is represented as a percentage of the LMD. Each LED segment represents 20% of the LMD.

In absolute mode, each segment represents a fixed amount of charge, based on the initial PFC. In absolute mode, each segment represents 20% of the PFC. As the battery wears out over time, it is possible for the LMD to be below the initial PFC. In this case, all of the LEDs may not turn on, representing the reduction in the actual battery capacity.

The capacity display is also adjusted for the present battery temperature. The temperature adjustment reflects the available capacity at a given temperature but does not affect the NAC register. The temperature adjustments are detailed in the TMPGG register description.

When  $\overline{\text{DISP}}$  is tied to V<sub>CC</sub>, the SEG<sub>1-5</sub> outputs are inactive. When  $\overline{\text{DISP}}$  is left floating, the display becomes active during charge if the NAC registers are counting at a rate equivalent to V<sub>SRO</sub> < -1mV or fast discharge if the NAC registers are counting at a rate equivalent to V<sub>SRO</sub> > 2mV. When pulled low, the segment output becomes active for 4 seconds, ±0.5 seconds.

The segment outputs are modulated as two banks, with segments 1, 3, and 5 alternating with segments 2 and 4. The segment outputs are modulated at approximately 320Hz, with each bank active for 30% of the period.

SEG<sub>1</sub> blinks at a 4Hz rate whenever V<sub>SB</sub> has been detected to be below V<sub>EDV</sub> to indicate a low-battery condition or NAC is less than 10% of the LMD or PFC, depending on the display mode.

### Microreregulator

The bq2011 can operate directly from 4 cells. To facilitate the power supply requirements of the bq2011, an REF output is provided to regulate an external low-threshold n-FET. A micropower source for the bq2011 can be inexpensively built using the FET and an external resistor.

## Absolute Maximum Ratings

Symbol	Parameter	Minimum	Maximum	Unit	Notes
V <sub>CC</sub>	Relative to V <sub>SS</sub>	-0.3	+7.0	V	
All other pins	Relative to V <sub>SS</sub>	-0.3	+7.0	V	
V <sub>SR</sub>	Relative to V <sub>SS</sub>	-0.3	+7.0	V	Minimum 100Ω series resistor should be used to protect SR in case of a shorted battery (see the bq2011 application note for details).
T <sub>OPR</sub>	Operating temperature	0	+70	°C	Commercial

**Note:** Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

## DC Voltage Thresholds (T<sub>A</sub> = T<sub>OPR</sub>; V = 3.0 to 6.5V)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
V <sub>EDV</sub>	End-of-discharge warning	0.87	0.90	0.93	V	SB
V <sub>SR1</sub>	Discharge compensation threshold	20	50	75	mV	SR (see note)
V <sub>SR2</sub>	Discharge compensation threshold	70	100	125	mV	SR (see note)
V <sub>SR3</sub>	Discharge compensation threshold	120	150	175	mV	SR (see note)
V <sub>SR4</sub>	Discharge compensation threshold	220	253	275	mV	SR (see note)
V <sub>SRQ</sub>	Valid charge	-	-	-400	μV	V <sub>SR</sub> + V <sub>OS</sub>
V <sub>SRD</sub>	Valid discharge	500	-	-	μV	V <sub>SR</sub> + V <sub>OS</sub>
V <sub>MCV</sub>	Maximum single-cell voltage	1.95	2.0	2.05	V	SB
V <sub>BR</sub>	Battery removed/replaced	-	0.1	0.25	V	SB

**Note:** For proper operation of the threshold detection circuit, V<sub>CC</sub> must be at least 1.5V greater than the voltage being measured.

## DC Electrical Characteristics (T<sub>A</sub> = T<sub>OPR</sub>)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
V <sub>CC</sub>	Supply voltage	3.0	4.25	6.5	V	V <sub>CC</sub> excursion from < 2.0V to ≥ 3.0V initializes the unit.
V <sub>OS</sub>	Offset referred to V <sub>SR</sub>	-	±50	±150	μV	DISP = V <sub>CC</sub>
V <sub>REF</sub>	Reference at 25°C	5.7	6.0	6.3	V	I <sub>REF</sub> = 5μA
	Reference at -40°C to +85°C	4.5	-	7.5	V	I <sub>REF</sub> = 5μA
R <sub>REF</sub>	Reference input impedance	2.0	5.0	-	MΩ	V <sub>REF</sub> = 3V
I <sub>CC</sub>	Normal operation	-	90	135	μA	V <sub>CC</sub> = 3.0V, DQ = 0
		-	120	180	μA	V <sub>CC</sub> = 4.25V, DQ = 0
		-	170	250	μA	V <sub>CC</sub> = 6.5V, DQ = 0
V <sub>SB</sub>	Battery input	0	-	V <sub>CC</sub>	V	
R <sub>SBmax</sub>	SB input impedance	10	-	-	MΩ	0 < V <sub>SB</sub> < V <sub>CC</sub>
I <sub>DISP</sub>	DISP input leakage	-	-	5	μA	V <sub>DISP</sub> = V <sub>SS</sub>
I <sub>MODE</sub>	MODE input leakage	-0.2	-	0.2	μA	DISP = V <sub>CC</sub>
I <sub>RBI</sub>	RBI data-retention current	-	-	100	nA	V <sub>RBI</sub> > V <sub>CC</sub> < 3V
R <sub>DQ</sub>	Internal pulldown	500	-	-	KΩ	
V <sub>SR</sub>	Sense resistor input	-0.3	-	2.0	V	V <sub>SR</sub> > V <sub>SS</sub> = discharge; V <sub>SR</sub> < V <sub>SS</sub> = charge
R <sub>SR</sub>	SR input impedance	10	-	-	MΩ	-200mV < V <sub>SR</sub> < V <sub>CC</sub>
V <sub>IHPFC</sub>	PFC logic input high	V <sub>CC</sub> - 0.2	-	-	V	PFC
V <sub>ILPFC</sub>	PFC logic input low	-	-	V <sub>SS</sub> + 0.2	V	PFC
V <sub>IZPFC</sub>	PFC logic input Z	float	-	float	V	PFC
I <sub>IHPFC</sub>	PFC input high current	-	1.2	-	μA	V <sub>PFC</sub> = V <sub>CC</sub> /2
I <sub>ILPFC</sub>	PFC input low current	-	1.2	-	μA	V <sub>PFC</sub> = V <sub>CC</sub> /2
V <sub>OLSL</sub>	SEG <sub>X</sub> output low, low V <sub>CC</sub>	-	0.1	-	V	V <sub>CC</sub> = 3V, I <sub>OLS</sub> ≤ 1.75mA SEG <sub>1</sub> -SEG <sub>5</sub>
V <sub>OLSH</sub>	SEG <sub>X</sub> output low, high V <sub>CC</sub>	-	0.4	-	V	V <sub>CC</sub> = 6.5V, I <sub>OLS</sub> ≤ 11.0mA SEG <sub>1</sub> -SEG <sub>5</sub>
V <sub>OHML</sub>	MODE output high, low V <sub>CC</sub>	V <sub>CC</sub> - 0.3	-	-	V	V <sub>CC</sub> = 3V, I <sub>OHMODE</sub> = -5.25mA
V <sub>OHMH</sub>	MODE output high, high V <sub>CC</sub>	V <sub>CC</sub> - 0.6	-	-	V	V <sub>CC</sub> = 6.5V, I <sub>OHMODE</sub> = -33.0mA
I <sub>OHMODE</sub>	MODE source current	-33	-	-	mA	At V <sub>OHMODE</sub> = V <sub>CC</sub> - 0.6V
I <sub>IOLS</sub>	SEG <sub>X</sub> sink current	11.0	-	-	mA	At V <sub>OLSH</sub> = 0.4V, V <sub>CC</sub> = 6.5V
I <sub>IOL</sub>	Open-drain sink current	5.0	-	-	mA	At V <sub>OL</sub> = V <sub>SS</sub> + 0.3V, DQ
V <sub>OL</sub>	Open-drain output low	-	-	0.5	V	I <sub>OL</sub> ≤ 5mA, DQ
V <sub>IHDQ</sub>	DQ input high	2.5	-	-	V	DQ
V <sub>ILDQ</sub>	DQ input low	-	-	0.8	V	DQ
R <sub>FLOAT</sub>	Float state external impedance	-	5	-	MΩ	PFC

**Note:** All voltages relative to V<sub>SS</sub>.



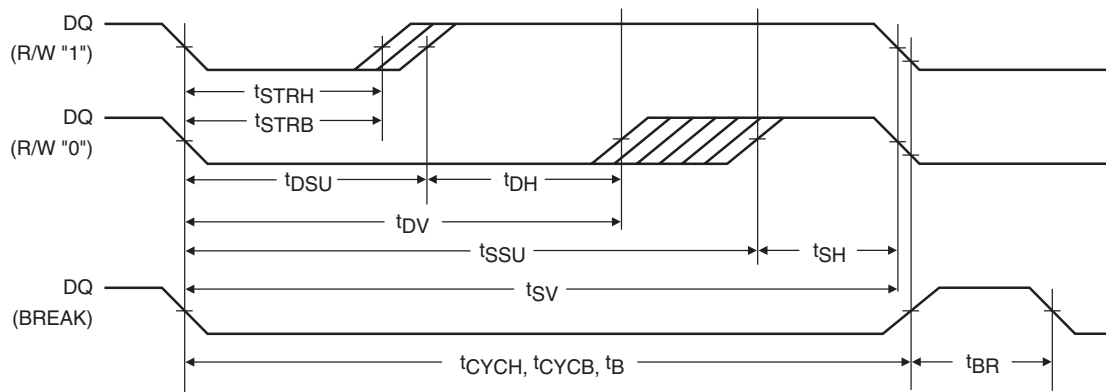
# bq2011

## Serial Communication Timing Specification (TA = TOPR)

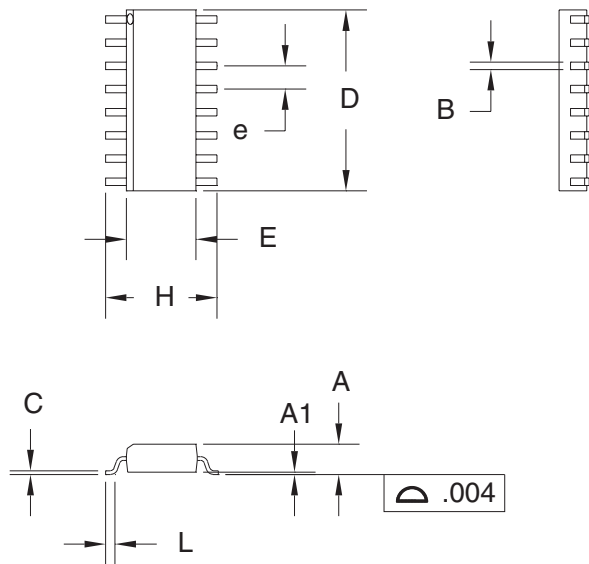
Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
tCYCH	Cycle time, host to bq2011	3	-	-	ms	See note
tCYCB	Cycle time, bq2011 to host	3	-	6	ms	
tSTRH	Start hold, host to bq2011	5	-	-	ns	
tSTRB	Start hold, bq2011 to host	500	-	-	μs	
tDSU	Data setup	-	-	750	μs	
tDH	Data hold	750	-	-	μs	
tDV	Data valid	1.50	-	-	ms	
tSSU	Stop setup	-	-	2.25	ms	
tSH	Stop hold	700	-	-	μs	
tSV	Stop valid	2.95	-	-	ms	
tB	Break	3	-	-	ms	
tBR	Break recovery	1	-	-	ms	

**Note:** The open-drain DQ pin should be pulled to at least V<sub>CC</sub> by the host system for proper DQ operation. DQ may be left floating if the serial interface is not used.

## Serial Communication Timing Illustration



16-Pin SOIC Narrow (SN)



16-Pin SN (SOIC Narrow)

Dimension	Minimum	Maximum
A	0.060	0.070
A1	0.004	0.010
B	0.013	0.020
C	0.007	0.010
D	0.385	0.400
E	0.150	0.160
e	0.045	0.055
H	0.225	0.245
L	0.015	0.035

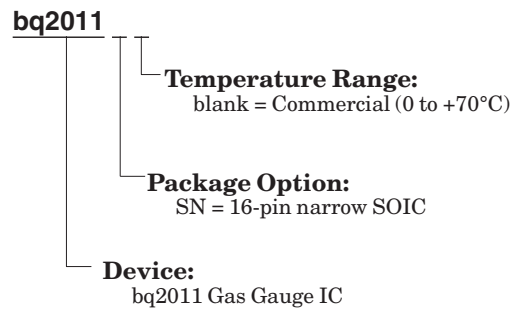
All dimensions are in inches.

## Data Sheet Revision History

Change No.	Page No.	Description	Nature of Change
3	7	Self-discharge count rate	Was: $\frac{1}{64}$ * NAC rate per day Is: $\frac{1}{80}$ * NAC rate per day
3	7	Compensation factor 30–40°C	Was: 0.90 Is: 0.95
3	7	Compensation factor >40°C	Was: 0.80 Is: 0.90
4	7	Charge compensation	Changed compensation factor variation with temperature
4	8	Self-discharge compensation	Changed self-discharge compensation rate variation with temperature

**Notes:** Changes 1 and 2 = See the *1995 Data Book*.  
 Change 3 = Jan. 1996 D changes from July 1994 C.  
 Change 4 = Feb. 1996 E changes from Jan. 1996 D.

## Ordering Information



**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
BQ2011SN-D118	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ2011SN-D118G4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ2011SN-D118TR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
BQ2011SN-D118TRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

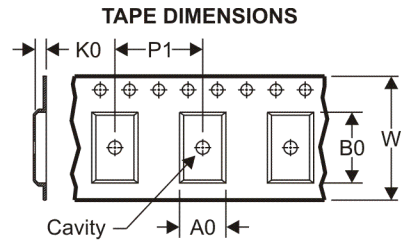
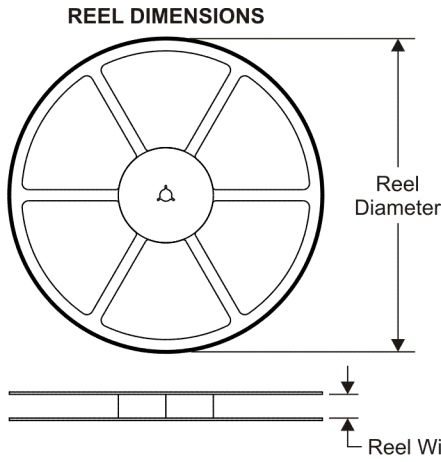
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

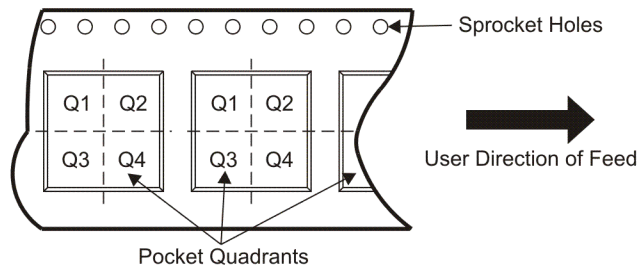
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

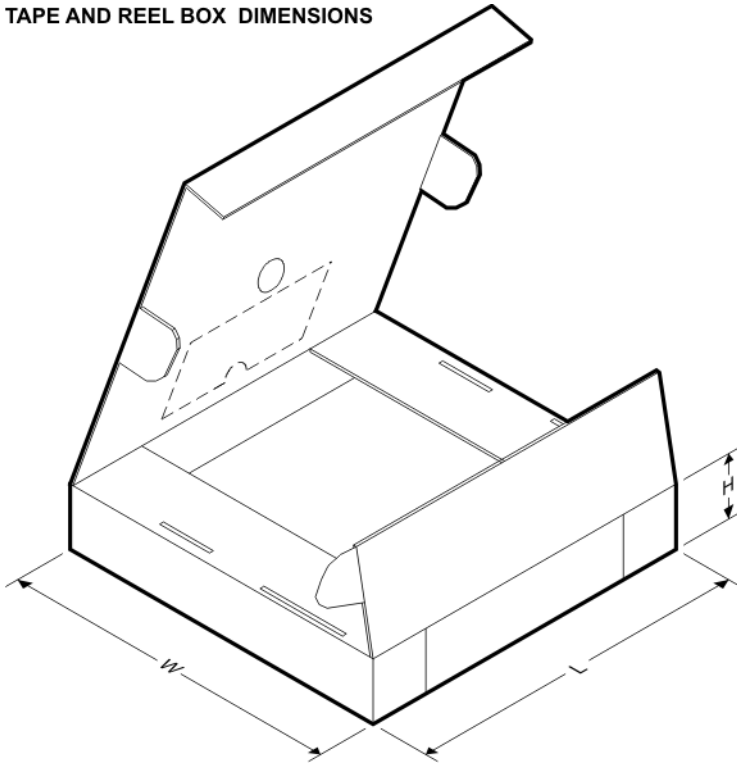
**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ2011SN-D118TR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

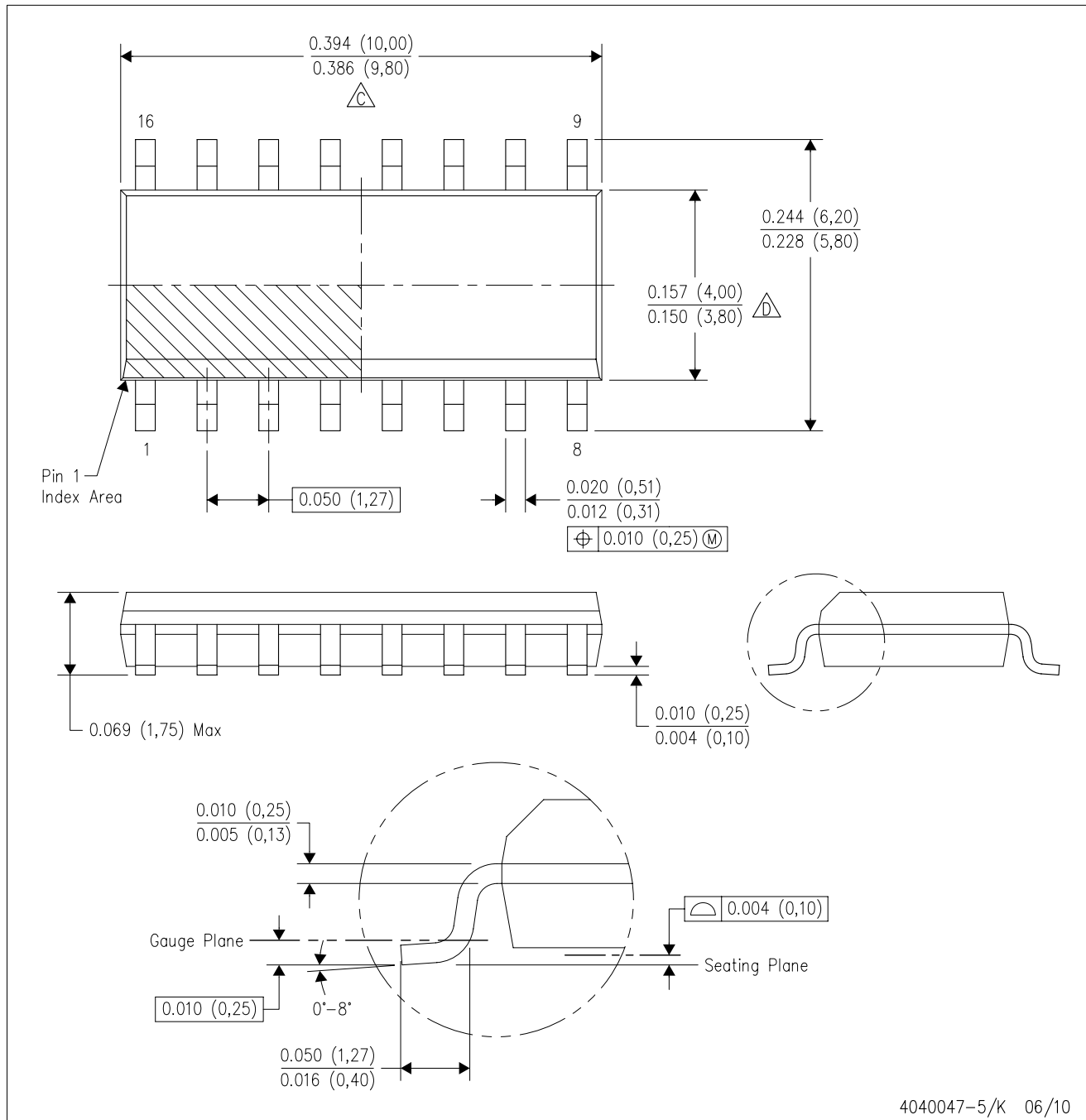


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ2011SN-D118TR	SOIC	D	16	2500	346.0	346.0	33.0

D (R-PDSO-G16)

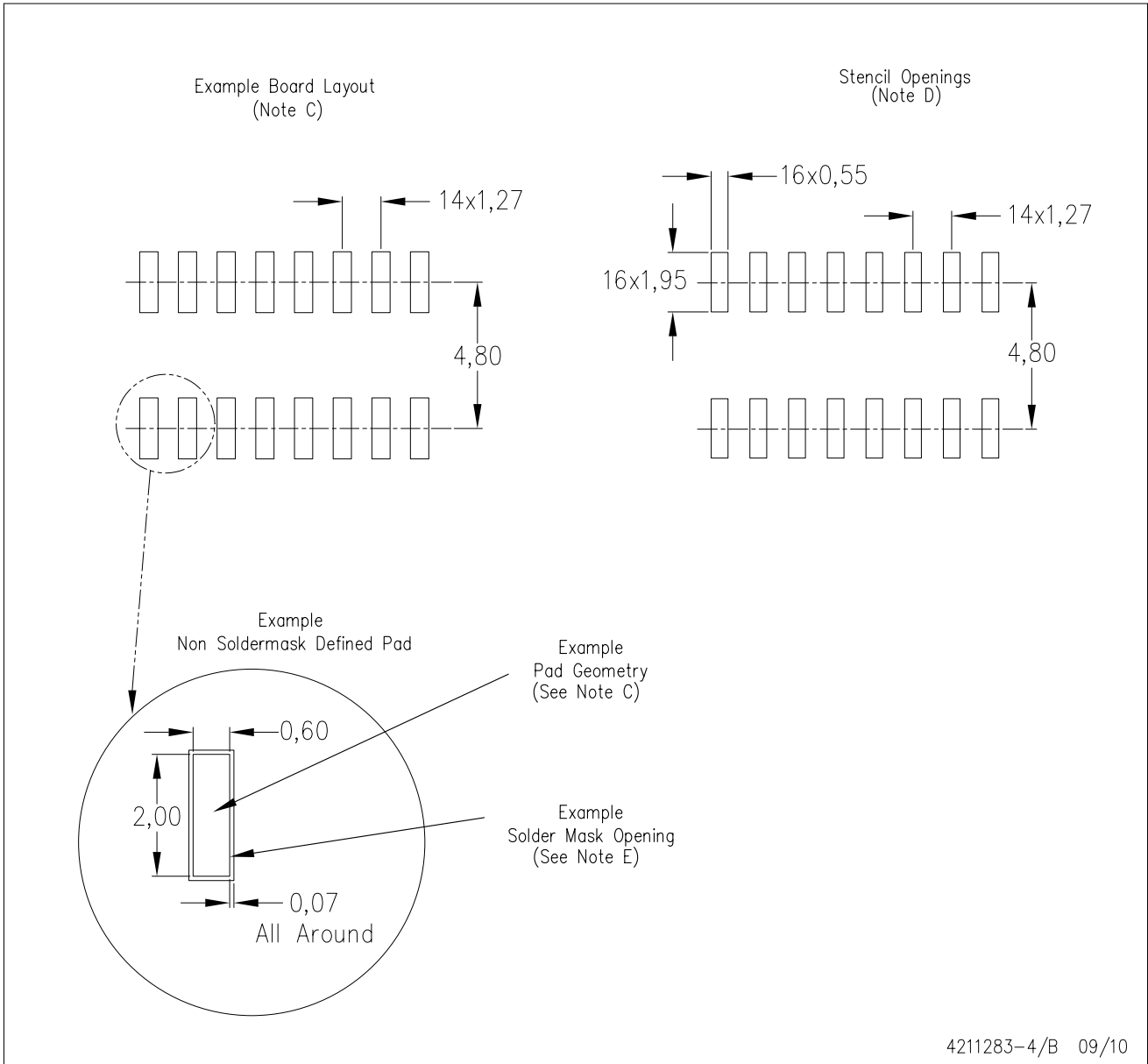
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate designs.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

<b>Products</b>		<b>Applications</b>	
Amplifiers	<a href="http://amplifier.ti.com">amplifier.ti.com</a>	Audio	<a href="http://www.ti.com/audio">www.ti.com/audio</a>
Data Converters	<a href="http://dataconverter.ti.com">dataconverter.ti.com</a>	Automotive	<a href="http://www.ti.com/automotive">www.ti.com/automotive</a>
DLP® Products	<a href="http://www.dlp.com">www.dlp.com</a>	Communications and Telecom	<a href="http://www.ti.com/communications">www.ti.com/communications</a>
DSP	<a href="http://dsp.ti.com">dsp.ti.com</a>	Computers and Peripherals	<a href="http://www.ti.com/computers">www.ti.com/computers</a>
Clocks and Timers	<a href="http://www.ti.com/clocks">www.ti.com/clocks</a>	Consumer Electronics	<a href="http://www.ti.com/consumer-apps">www.ti.com/consumer-apps</a>
Interface	<a href="http://interface.ti.com">interface.ti.com</a>	Energy	<a href="http://www.ti.com/energy">www.ti.com/energy</a>
Logic	<a href="http://logic.ti.com">logic.ti.com</a>	Industrial	<a href="http://www.ti.com/industrial">www.ti.com/industrial</a>
Power Mgmt	<a href="http://power.ti.com">power.ti.com</a>	Medical	<a href="http://www.ti.com/medical">www.ti.com/medical</a>
Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Space, Avionics & Defense	<a href="http://www.ti.com/space-avionics-defense">www.ti.com/space-avionics-defense</a>
RF/IF and ZigBee® Solutions	<a href="http://www.ti.com/lprf">www.ti.com/lprf</a>	Video and Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
		Wireless	<a href="http://www.ti.com/wireless-apps">www.ti.com/wireless-apps</a>

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2010, Texas Instruments Incorporated

[www.BDTIC.com/TI](http://www.BDTIC.com/TI)